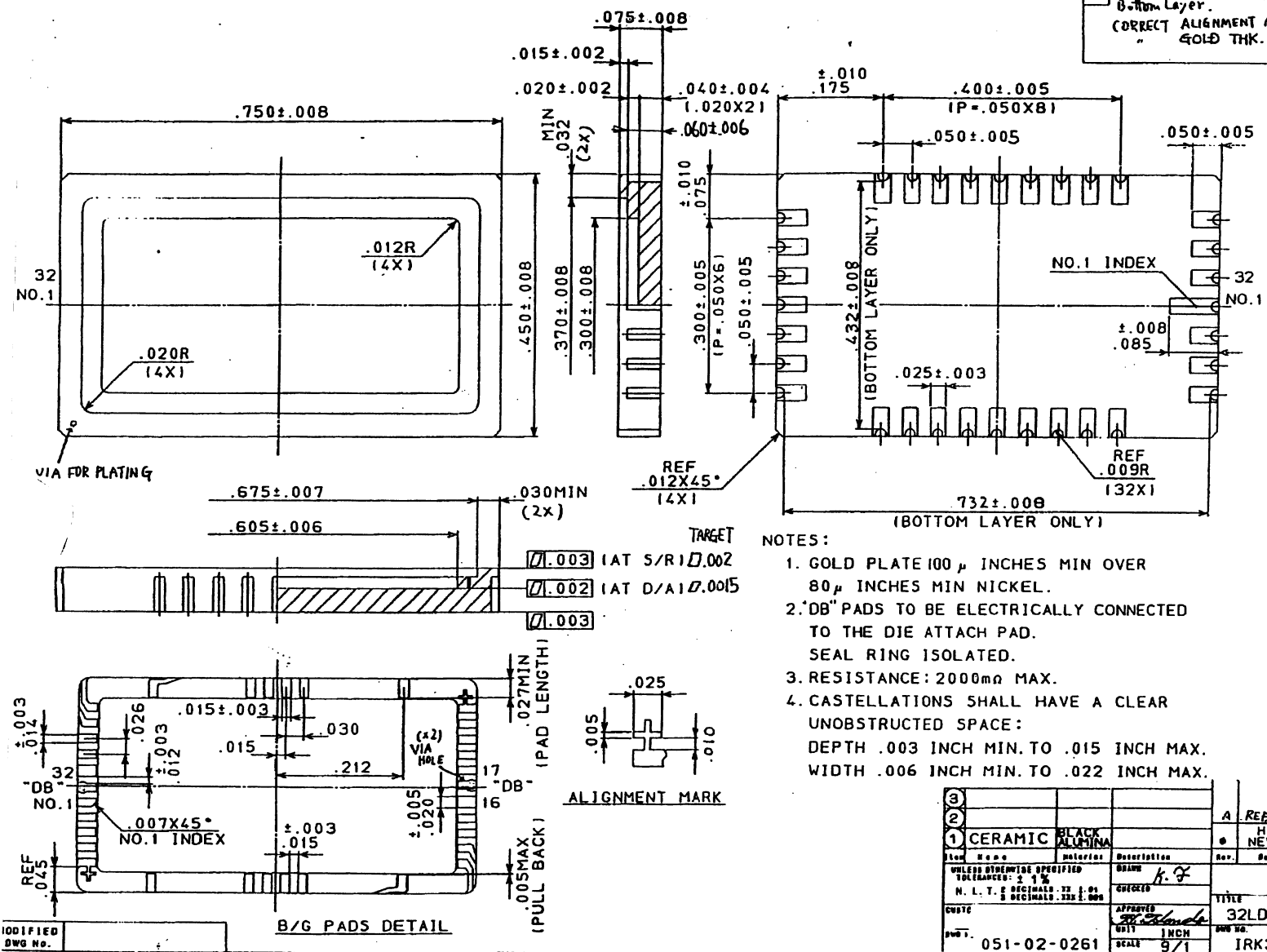


SSM P/N LCC03237

LATEST REVISION'S DESCRIPTION
A CHG DIM BETWEEN CASTELLATIONS AT Bottom Layer.
 CORRECT ALIGNMENT MARK DIM.
 GOLD THK. 100μM:MIN WAS 80μM:MIN



- NOTES:
1. GOLD PLATE 100 μ INCHES MIN OVER 80 μ INCHES MIN NICKEL.
 2. "DB" PADS TO BE ELECTRICALLY CONNECTED TO THE DIE ATTACH PAD. SEAL RING ISOLATED.
 3. RESISTANCE: 2000mΩ MAX.
 4. CASTELLATIONS SHALL HAVE A CLEAR UNOBSTRUCTED SPACE: DEPTH .003 INCH MIN. TO .015 INCH MAX. WIDTH .006 INCH MIN. TO .022 INCH MAX.

3							
2							
1	CERAMIC	BLACK ALUMINA					
REV	NO	DATE	DESCRIPTION	BY	DATE	DESCRIPTION	DATE
UNLESS OTHERWISE SPECIFIED				DRAWN			
TOLERANCES: ± 1%				CHECKED			
N. L. T. & DECIMALS: XX & .01				APPROVED			
3 DECIMALS: XXX & .001				SCALE			
CUSTC		PART		TITLE		REV	
051-02-0261		INCH		32LD CHIP CARRIER		B171	
		SCALE 9/1		IRK32F1-5434A		A-C	

